

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

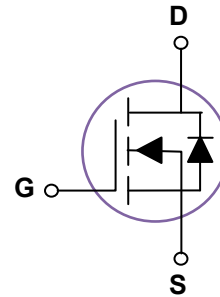
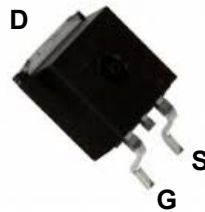
$V_{DS}$	70V
$I_D$ (at $V_{GS}=10V$ )	80A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	7m $\Omega$ (Typ)

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**

TO220



TO263



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	70	V
Gate-Source Voltage	$V_{GS}$	$\pm 25$	V
Drain Current-Continuous	TC=25°C	$I_D$ 80	A
	TC=100°C	$I_D$ 51	A
Drain Current – Pulsed	$I_{DM}$	360	A
Maximum Power Dissipation	$P_D$	176	W
Single pulse avalanche energy <sup>(1)</sup>	$E_{AS}$	480	mJ
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta JC}$		1.1	°C /W
Thermal Resistance unction-to-Ambient	$R_{\theta JA}$		62	°C /W

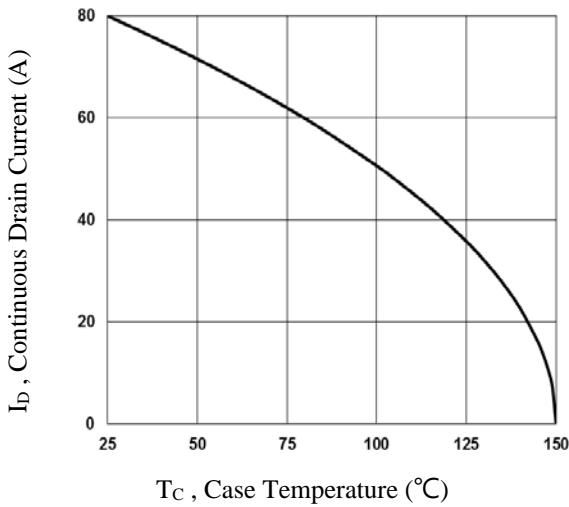
**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	70			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =70V, V <sub>GS</sub> =0V			1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		7	8	mΩ
<b>DYNAMIC PARAMETERS</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, F=1.0MHz		3000		pF
C <sub>OSS</sub>	Output Capacitance			350		pF
C <sub>rSS</sub>	Reverse Transfer Capacitance			190		pF
<b>SWITCHING PARAMETERS</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =40V, I <sub>D</sub> =1A, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω		14		nS
t <sub>r</sub>	Turn-on Rise Time			15		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			28		nS
t <sub>f</sub>	Turn-Off Fall Time			50		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, I <sub>D</sub> =10A, V <sub>GS</sub> =10V		65		nC
Q <sub>gs</sub>	Gate-Source Charge			12		nC
Q <sub>gd</sub>	Gate-Drain Charge			20		nC
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>SD</sub> =10A		0.72	1.4	V
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz		1.45		Ω

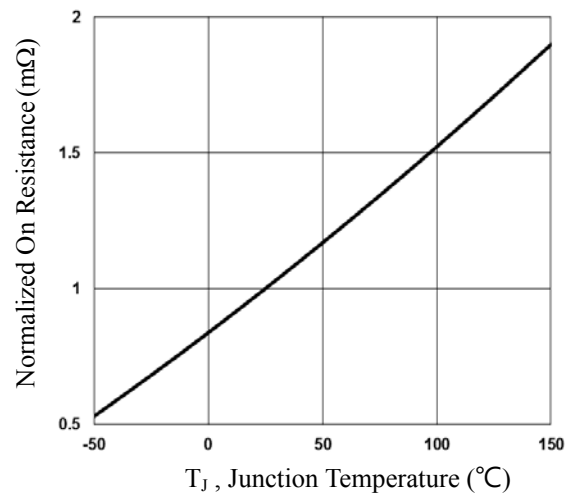
**Note:**

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=48V, V<sub>GS</sub>=10V, L=0.5mH, I<sub>AS</sub>=35A, Starting T<sub>J</sub>=25°C
3. The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%.
4. Essentially independent of operating temperature.

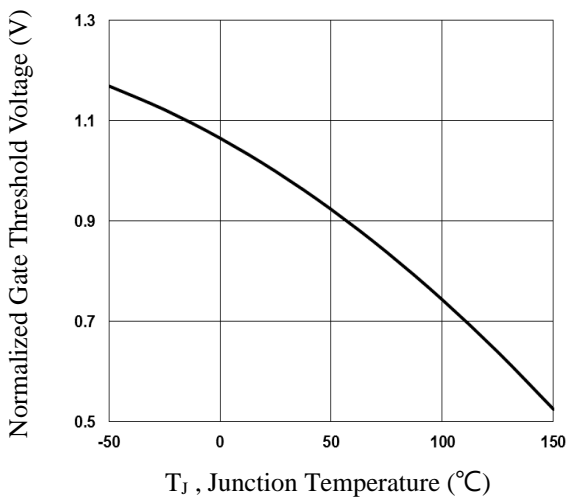
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



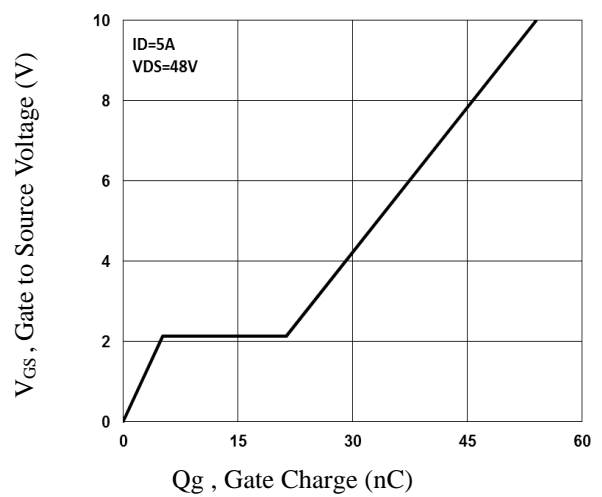
**Fig.1 Continuous Drain Current vs.  $T_c$**



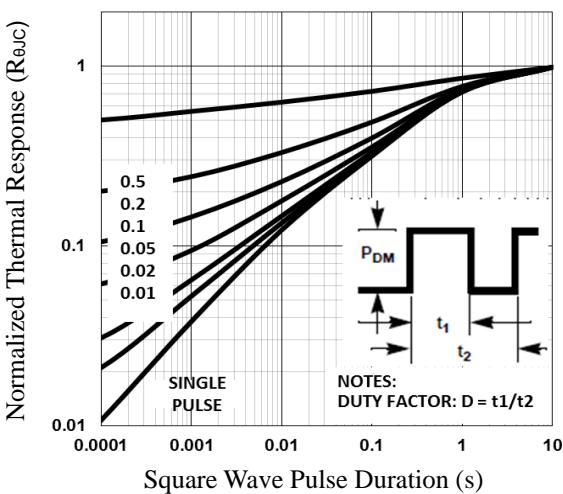
**Fig.2 Normalized RDSON vs.  $T_j$**



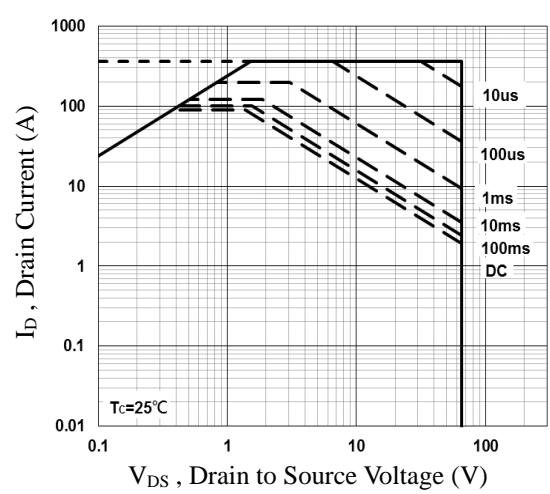
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



**Fig.4 Gate Charge Characteristics**

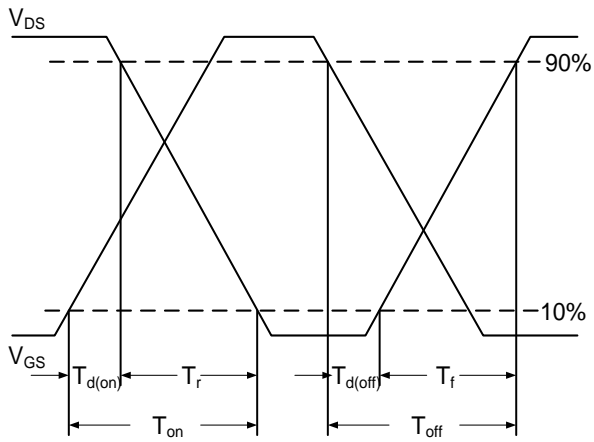


**Fig.5 Normalized Transient Impedance**

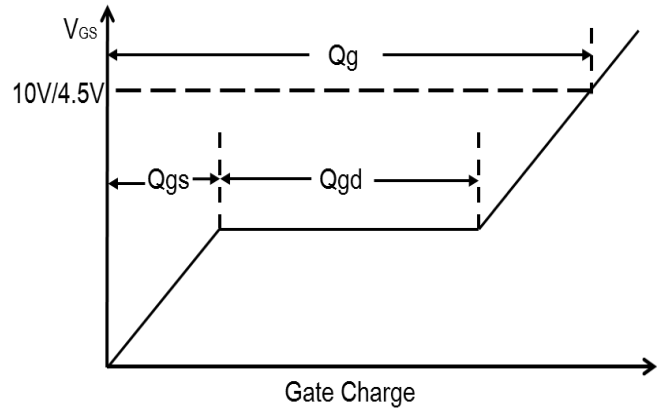


**Fig.6 Maximum Safe Operation Area**

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

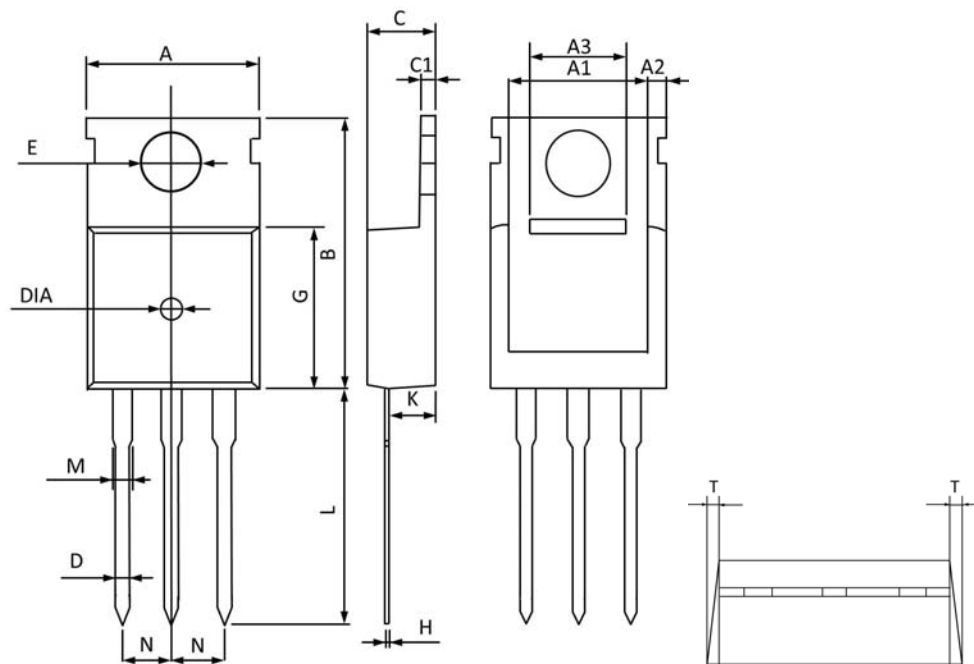


**Fig.7 Switching Time Waveform**



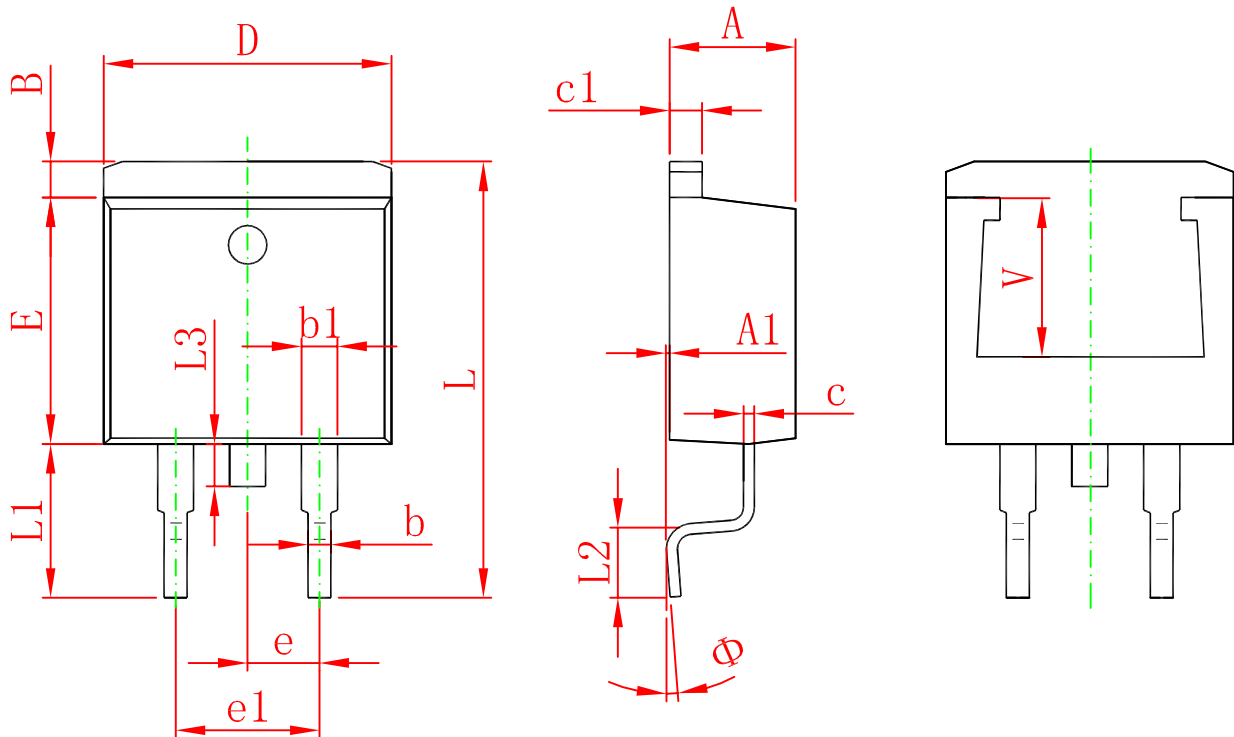
**Fig.8 Gate Charge Waveform**

TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.

TO263 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
$\Phi$	0°	8°	0°	8°
V	5.600 REF.		0.220 REF.	

Shanghai Leiditech Electronic Co.,Ltd  
 Email: sale1@leiditech.com  
 Tel : +86- 021 50828806  
 Fax : +86- 021 50477059